Multilayer Organic (MLO™)

0805 WLAN/BT Diplexer

MLO™ TECHNOLOGY

The 0805 MLO™ diplexer is best in class low profile multilayer organic passive device that is based on AVX's patented multilayer organic high density interconnect technology. The MLO™ diplexer uses high dielectric constant and low loss materials to realize high Q passive printed elements such as inductors and capacitors in a multilayer stack up. The MLO™ diplexers can support multiple wireless standards such as WCDMA, CDMA, WLAN and GSM. These components which are less than 0.5mm in thickness are ideally suited for band switching for dual band systems. All MLO™ diplexers are expansion matched to FR4 thereby resulting in improved reliability over standard Si and ceramic devices.

APPLICATIONS

Multiband applications including WiFi, BT, WiMax, GPS, and cellular bands

LAND GRID ARRAY ADVANTAGES

- Low Insertion Loss
- Excellent Solderability
- Low Parasitics
- Matched CTE to PCB

HOW TO ORDER

DP	05	A	5425	7	TR
Type	Size	Design	Frequency (MHz)	Finish	Packaging
				7 = Au T = NiSn	Tape & Reel TR = 3 Kpcs TR/500 = 500 pcs

QUALITY INSPECTION

Finished parts are 100% tested for electrical parameters and visual characteristics.

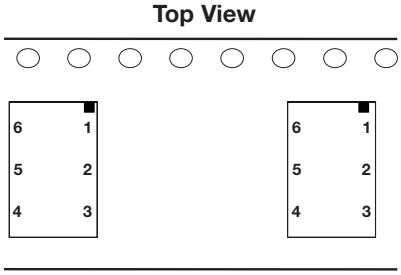
OPERATING TEMPERATURE

-40ºC to +85ºC

TERMINATION

Finishes available in Ni/Sn, Immersion Sn, Immersion Au and OSP coatings which are compatible with automatic soldering technologies which include reflow, wave soldering, vapor phase and manual.

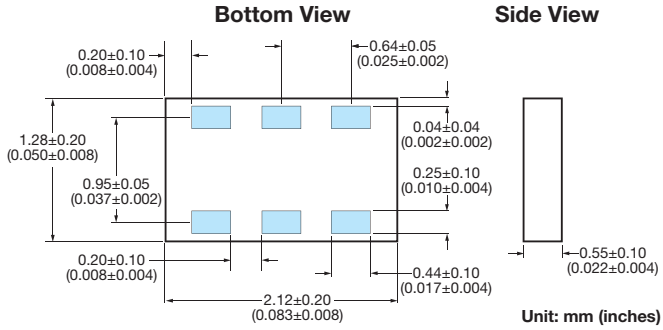
ORIENTATION IN TAPE



POWER CAPACITY

4.5W Maximum

COMPONENT DIMENSIONS AND FUNCTIONS

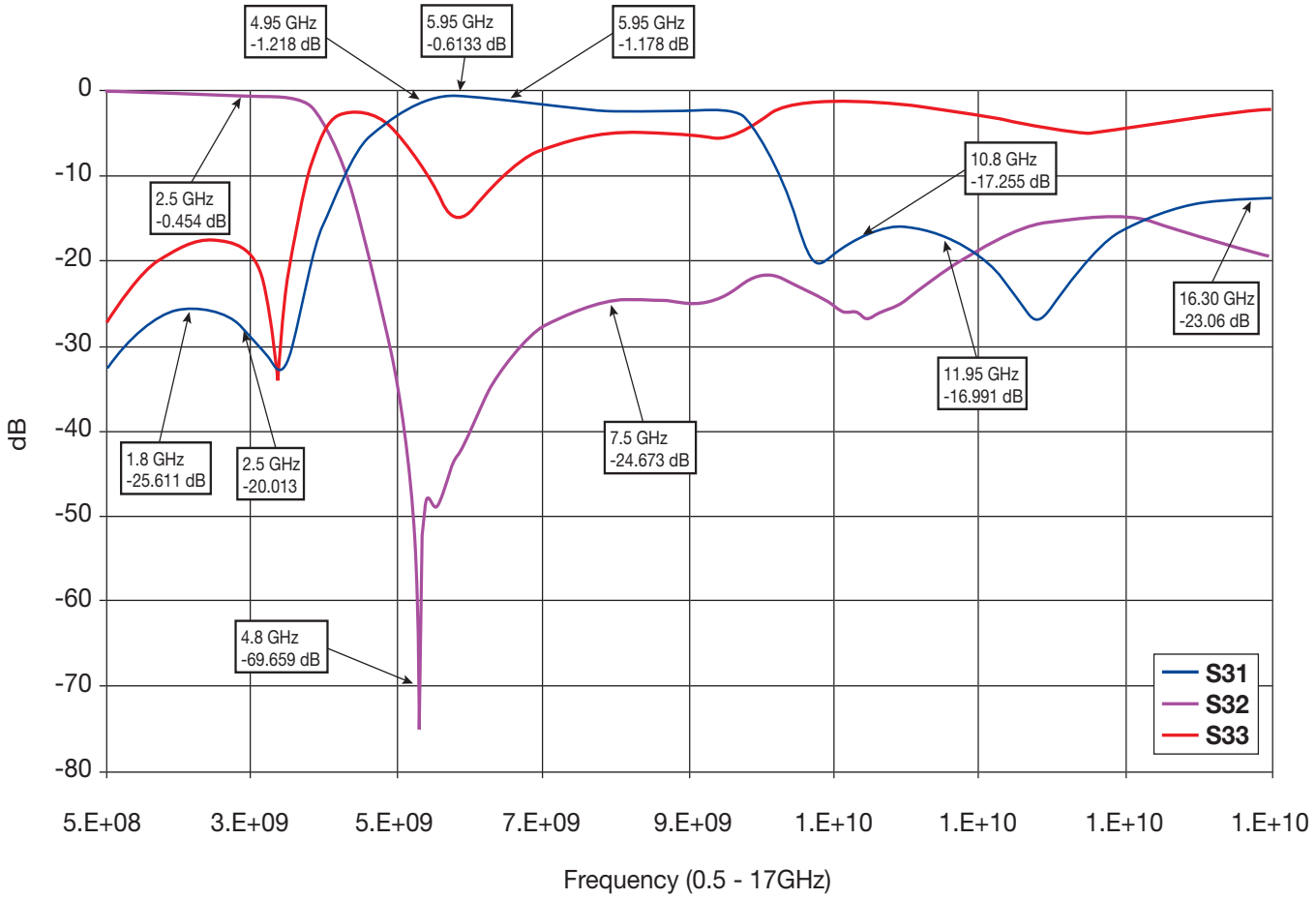


Terminal No.	Terminal Name
1	High Frequency Port
2	GND
3	Low Frequency Port
4	GND
5	Common Port
6	GND

PART NUMBER: DP05B54257TR

Specification @ 25ºC	
Size [mm(inches)]	2.12 x 1.28 (0.083 x 0.050)
Height [mm(inches)]	0.55 (0.021)
Volume (mm^3)	1.5
Pass Band Range (F1) (MHz)	2450 +/-50MHz
Pass Band Range (F2) (MHz)	5425 +/-525MHz
Insertion Loss (F1) (dB)	-0.5
Insertion Loss (F2) (dB)	-0.8
Attenuation (F1) 4800MHz - 6000MHz (dB)	-36
Attenuation 3 x (F1) (dB)	-31
Attenuation (F2) 1800MHz - 2500MHz (dB)	-26
Attenuation 2 x (F2) (dB)	-13
Attenuation 3 x (F2) (dB)	-15
VSWR (Input @ F1)	1.2
VSWR (Input @ F2)	1.7
VSWR (Lowband @ F1)	1.2
VSWR (Highband @ F2)	1.7

S PARAMETER MEASUREMENTS



AUTOMATED SMT ASSEMBLY

The following section describes the guidelines for automated SMT assembly of MLO™ RF devices which are typically Land Grid Array (LGA) packages or side termination SMT pacages.

Control of solder and solder paste volume is critical for surface mount assembly of MLO™ RF devices onto the PCB. Stencil thickness and aperture openings should be adjusted according to the optimal solder volume. The following are general recommendations for SMT mounting of MLO™ devices onto the PCB.

SMT REFLOW PROFILE

Common IR or convection reflow SMT processes shall be used for the assembly. Standard SMT reflow profiles, for eutectic and Pb free solders, can be used to surface mount the MLO™ devices onto the PCB. In all cases, a temperature gradient of 3°C/sec, or less, should be maintained to prevent warpage of the package and to ensure that all joints reflow properly. Additional soak time and slower preheating time may be required to improve the out-gassing of solder paste. In addition, the reflow profile depends on the PCB density and the type of solder paste used. Standard no-clean solder paste is generally recommended. If another type of flux is used, complete removal of flux residual may be necessary. Example of a typical lead free reflow profile is shown below.

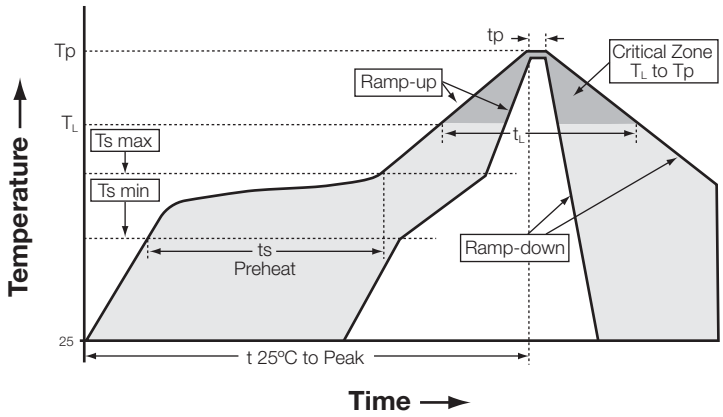


Figure A. Typical Lead Free Profile and Parameters

Profile Parameter	Pb free, Convection, IR/Convection
Ramp-up rate (Tsmax to Tp	3ºC/second max.
Preheat temperature (Ts min to Ts max)	150ºC to 200ºC
Preheat time (ts)	60 – 180 seconds
Time above T_L, 217ºC (t_L)	60 – 120 seconds
Peak temperature (Tp)	260°C
Time within 5ºC of peak temperature (tp)	10 – 20 seconds
Ramp-down rate	4ºC/second max.
Time 25ºC to peak temperature	6 minutes max.

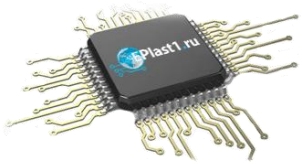
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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